



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD208-B1-02EL E6327		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA001614268						
<b>Package</b>		PG-TSLP-2-19		<b>Weight*</b>		0.61 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.06		575	
	noble metal	gold	7440-57-5	0.001	0.22		2227	
	inorganic material	silicon	7440-21-3	0.011	1.81	2.09	18062	20864
leadframe	non noble metal	nickel	7440-02-0	0.241	39.63	39.63	396274	396274
wire	non noble metal	copper	7440-50-8	0.003	0.43	0.43	4255	4255
encapsulation	organic material	carbon black	1333-86-4	0.002	0.27		2695	
	plastics	epoxy resin	-	0.047	7.81		78148	
	inorganic material	silicondioxide	60676-86-0	0.278	45.80	53.88	458109	538952
leadfinish	noble metal	gold	7440-57-5	0.010	1.72	1.72	17159	17159
plating	noble metal	palladium	7440-05-3	0.003	0.53		5337	
	noble metal	gold	7440-57-5	0.010	1.72	2.25	17159	22496
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com